SHARP

Spec No.	DG-10Y029B
Issue	22-Feb-11

S P E C I F I C A T I O N S

Product Type

ZENIGATA LED

Model No.

GW5D*C**M04

*C** : MC27, MC30, MC35 LC40, LC50, LC65

Reference

*These specifications contain <u>20</u> pages including the cover and appendix. If you have any objections, please contact us before issuing purchasing order.

CUSTOMERS ACCEPTANCE

DATE:

BY:

PRESENTED

BY: Y. Ohiwane Dept. General Manager

REVIEWED BY:

PREPARED BY:

Development Department II System Device Division III Electronic Components And Devices Group SHARP CORPORATION

Model No. **GW5D*C**M04**



• Handle this document carefully for it contains material protected by international copyright law. Any reproduction, full or in part, of this material is prohibited without the express written permission of the company.

• When using the products covered herein, please observe the conditions written herein and the precautions outlined in the following paragraphs. In no event shall the company be liable for any damages resulting form failure to strictly adhere to these conditions and precautions.

(1) Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.

(2) The products covered herein are designed and manufactured for the following application areas. When using the products covered herein for the equipment listed in paragraph (3), even for the following application areas, be sure to observe the precautions given in Paragraph (3). Never use the products for the equipment listed in Paragraph (4).

- \cdot Office electronics
- ·Instrumentation and measuring equipment
- Machine tools
- ·Audiovisual equipment
- Home appliances
- ·Communication equipment other than for trunk lines
- (3) These contemplating using the products covered herein for the following

equipment which demands high reliability, should first contact a sales representative of the company and then accept responsibility for incorporating into the design fail-safe operation, redundancy, and other appropriate measures for ensuring reliability and safety of the equipment and the overall system.

·Control and safety devices for airplanes, trains, automobiles, and other

- transportation equipment
- · Mainframe computers
- ·traffic control systems
- ·Gas leak detectors and automatic cutoff devices
- ·Rescue and security equipment
- ·Other safety devices and safety equipment, etc.

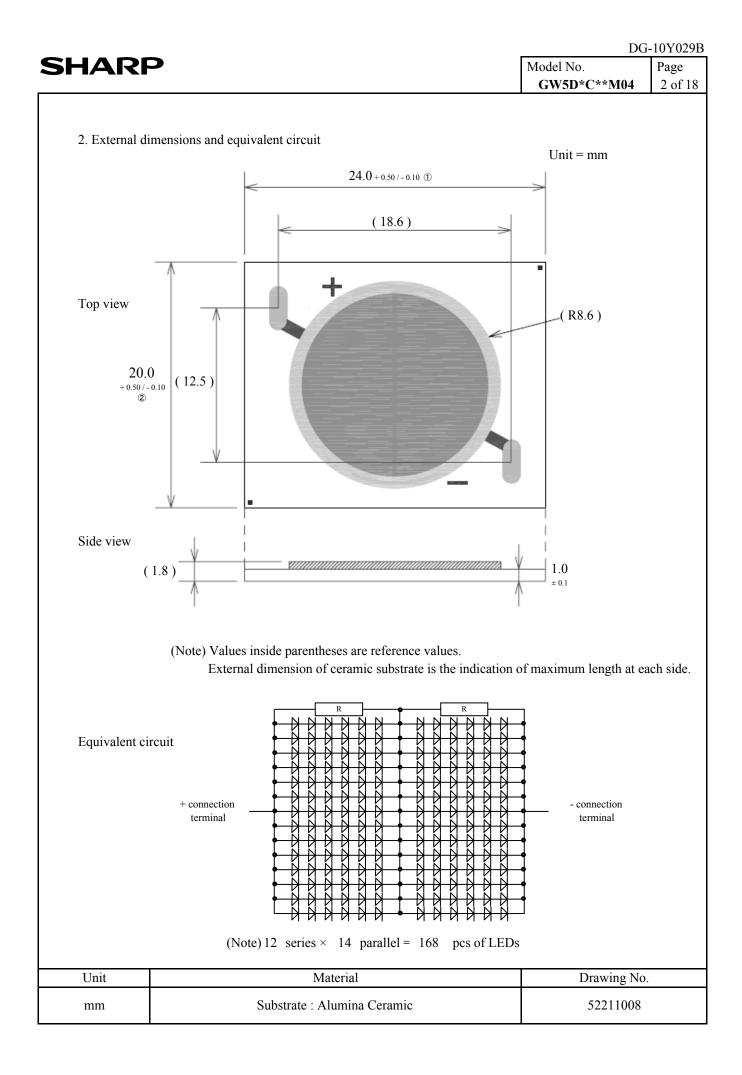
(4) Do not use the products covered herein for the following equipment which

demands extremely high performance in terms of functionality, reliability, or accuracy.

- ·Aerospace equipment
- ·Communications equipment for trunk lines
- ·Control equipment for the nuclear power industry
- ·Medical equipment related to life support, etc.
- (5) please direct all queries and comments regarding the interpretation of the above four Paragraphs to a sales representative of the company.

 Please direct all queries regarding the products covered herein to a sales representative of the company.

HARP <u>GW5D*C**M04 specificat</u> 1. Application	Model No. GW5D*C**M04	Page 1 or
1. Application		10
1. Application	tions	
1. Application	ions	
1. Application	ions	
These specifications apply to the light emitting diode module M [LED module (InGaN Blue LED chip + Phosphor)] Main application : Lighting	lodel No. GW5D*C**M04.	
2. External dimensions and equivalent circuit	Refer to Page 2.	
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3-2. Electro-optical characteristics		
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4. Reliability	Defer to Deco 6	
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4-1. Failure criteria		
5. Quality level	Refer to Page 7.	
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6-1. Chromaticity rank table		
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6-3. Label		
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7. Precautions	Refer to Page 15 - 17.	
2 Characteristics discusses (TVD)	Defende Dere 10	
8. Characteristics diagram (TYP.)	Refer to Page 18.	



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- 3. Ratings and characteristics
- 3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power Dissipation *1,4	Р	33.6	W
Forward Current *1,4	I _F	840	mA
Reverse Voltage *2,4	V _R	-15	V
Operating Temperature *3	T _{opr}	- 30 ~ + 100	°C
Storage Temperature	T _{stg}	- 40 ~ + 100	°C

*1 Power dissipation and forward current are the value when the module temperature is set lower than the rating by using an adequate heat sink.

- *2 Voltage resistible at initial connection error (Not dealing with the possibility of always-on reverse voltage.)
- *3 Case temperature Tc (Refer to measuring point for case temperature in the next page.) Refer to "Derating curve" in the next page as for operating current.

*4 T_c = 25 $^{\circ}$ C

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3-2. Electro-optical characteristics

						(T _c	= 25 °C
**	Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
common	Forward Voltage *5	V _F	$I_F = 700 \text{ mA}$	34	(37)	40	V
	Luminous Flux *6	Φ		2000	(2300)	-	lm
	Chromaticity Coordinates *7	х		-	(0.464)	-	-
27	Chromaticity Coordinates • 7	у	$I_F = 700 \text{ mA}$	-	(0.418)	-	-
	Color Temperature	-		(2600)	(2700)	(2800)	Κ
	General Color Rendering Index *8	Ra		80	(83)	-	-
	Luminous Flux *6	Φ		2070	(2370)	-	lm
	Chromaticity Coordinates *7	x		-	(0.435)	-	-
30	Chromaticity Coordinates • 7	у	$I_F = 700 \text{ mA}$	-	(0.403)	-	-
	Color Temperature	-		(2900)	(3025)	(3150)	Κ
	General Color Rendering Index *8	Ra		80	(83)	-	-
	Luminous Flux *6	Φ		2150	(2450)	-	lm
	Chromaticity Coordinates *7	х	$I_F = 700 \text{ mA}$	-	(0.409)	-	-
35	Chromaticity Coordinates • 7	у		-	(0.393)	-	-
	Color Temperature	-		(3300)	(3450)	(3600)	Κ
	General Color Rendering Index *8	Ra		80	(83)	-	-
	Luminous Flux *6	Φ		2250	(2550)	-	lm
	Chromaticity Coordinates *7	х	$I_{\rm F} = 700 {\rm mA}$	-	(0.381)	-	-
40	Chromaticity Coordinates • 7	у		-	(0.383)	-	-
	Color Temperature	-		(3900)	(4050)	(4200)	K
	General Color Rendering Index *8	Ra		80	(82)	-	-
	Luminous Flux *6	Φ		2300	(2600)	-	lm
	Chromaticity Coordinates *7	Х		-	(0.346)	-	-
50	Chromaticity Coordinates • 7	у	$I_F = \ 700 \ mA$	-	(0.360)	-	-
	Color Temperature	-		(4745)	(5000)	(5311)	Κ
	General Color Rendering Index *8	Ra		80	(82)	-	-
	Luminous Flux *6	Φ		2300	(2600)	-	lm
	Chromaticity Coordinates *7	x		-	(0.313)	-	-
65		у	$I_F = 700 \text{ mA}$	-	(0.332)	_	-
	Color Temperature	-		(6020)	(6500)	(7040)	Κ
	General Color Rendering Index *8	Ra		80	(82)	-	-

(Note) Values inside parentheses are shown for reference purpose only.

*5 (After 20 ms drive, Measurement tolerance: ± 3 %)

- *6 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 10 %)
- *7 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 0.005)
- *8 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 2)

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ARF													odel		
												(GW.	5D*C	**]
3. Derating	curve														
8															
				Forv	vard	Curre	ent De	rating	o Cur	ve					
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1000				- L	<u> </u> -	L -					 	- 		L	
200															
⁸⁰⁰ ک				-								\			
Forward Current I _F [mA]		 	·		+ - + -		· ·	- - - - · - - - - ·	- + - + - + - +		 · ·		×	· - + - ·	
000 II I															
urre				- <u>-</u>	L _					L	 	 	L	<u>L</u>	
Б 400										+ I			1	- +	
war				- +	 -		·				 		+	- +	
For		 - -	-	- I	 -						 	 + - + -	+ -	 +	

(Note) To keep the case temperature lower than the rating, enough heat-radiation performance needs to be secured by using an adequate heat sink.

40

Case Temperature T_c [°C]

50

60

70

80

90

100 110

20

10

30

For soldering connection, please evaluate in your circumstance to make sure soldering reliability. (Above derating curve is specified to LED device, not for soldering connection) And please consider to avoid physical stress between wire and substrate, and some protection like silicon bond on top of soldered wire is recommended.

Please ensure the maintenance of heat radiation not to exceed case temperature over the rating in operation.

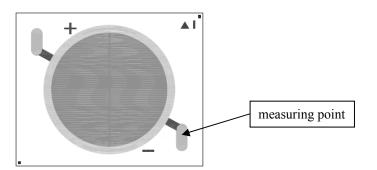
(Measuring point for case temperature)

200

0

-30 -20 -10

0



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SHARP	
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4. Reliability

The reliability of products shall be satisfied with items listed below.

4-1.7	Test items and test condit	ions	Co	nfidence le	vel: 90 %
No.	Test item	Test conditions	Samples	Defective	LTPD
			n	С	(%)
1	Temperature Cycle	- 40 °C(30 min) \sim + 100 °C(30 min), 100 cycles			
			11	0	20
2	Temperature Humidity	$T_{stg} = +60$ °C, RH = 90 %, Time = 1000 h			
	Storage		11	0	20
3	High Temperature	$T_{stg} = +100$ °C, Time = 1000 h			
	Storage		11	0	20
4	Low Temperature	$T_{stg} = -40 \text{ °C}, \text{ Time} = 1000 \text{ h}$			
	Storage		11	0	20
5	Steady State Operating	$T_c = 60 \ ^{\circ}C$, $I_F = 770 \ mA$, Time = 1000 h			
	Life		11	0	20
6	Shock	Acceleration: 15000 m/s^2 , Pulse width: 0.5 ms			
		Direction: 3 directions (X, Y and Z)			
		3 trials in each direction	5	0	50
7	Vibration	Frequency: 100 to 2000 Hz for 4 minutes per trial			
		Acceleration: 200 m/s ²			
		Direction: 3 directions (X, Y and Z)			
		4 trials in each direction	5	0	50

4-2. Failure criteria

		411410 01100114		
	No.	Parameter	Symbol	Failure criteria
ſ	1	Forward Voltage	V _F	$V_F > Initial value \times 1.1$
	2	Luminous Flux	Φ	Φ < Initial value × 0.7

HA	RP]	Model No. GW5D*C**N		0Y029 Page 7 of 18
5-1. A IS 5-2. S	ality level Applied standard O2859-1 Sampling inspecti single normal sa	on mpling plan, level S-4.			
	nspection items a	nd defect criteria			_
No.	Item	Defect criteria	Classification	AQL	
1	No radiation	No light emitting	Major defect	0.1%	
2	Electro-optical characteristics	Not conforming to the specification (Forward voltage, Luminous flux and Chromaticity)			
3	External dimensions	Not conforming to the specified dimensions (External dimensions of ① and ② shown in Page 2)			
4	Appearance	 Nonconformity observed in product appearance is determined as defective only when electro-optical characteristics is affected by. <if above="" any="" arises="" criterion="" mentioned="" of="" question="" regardless=""></if> Foreign material, scratch, or bubble at emitting area: 0.8 mm φ Fiber generation at emitting area: 0.2 mm in width and 2.5 mm in length 	Minor defect	0.4%	
		 Foreign material at connection terminal: 0.8 mm φ Substrate burr on edge: Over dimension tolerance 			

 Substrate burr on edge: Over dimension tolerance

 (Note) Products with removable foreign material attached on is not determined to be defective.

						I		G-10
IARF							Model No. GW5D*C**M04	Ра 8
6. Supplemen	its							
6-1. Chroma	ticity rank ta	ıble					$x,y \pm 0.005)$	
**: 27					$(I_F = 7)$	700 mA	$, T_{c} = 25 $ °C)	
D		Chromaticity	coordinat	tes				
Range	Poin	t 1 Point 2	Point 3	Point 4				
	x 0.46		0.4669	0.4756				
	y 0.42	0.4100	0.4100	0.4250				
			1:					
Rank	Poin	Chromaticity t 1 Point 2	Point 3	tes Point 4				
	x 0.46		0.4595	0.4679				
1	y 0.42		0.4100	0.4250				
2 —	x 0.46		0.4669	0.4756				
	y 0.42	250 0.4100 k in the shipmen	0.4100	0.4250				
0.440			maticity Dia	gram				
	·	, , , , , , , , , , , , , , , , , , ,				/ /		
0.420			;		;			
0.430			/				/	
						7		
> 0.420	·k			/	·			
	i				2	1		
	·	·/-:/		-/	/		<u></u>	
1								
0.410	·	2800K	2700K	2600K				
	·					<u>-</u>		
	;			;	1			
0.400 L 0.440		0.450	0.460		0.470		0.480	
0.440		0.750	0.400 X		0.770		0.700	

							DC	G-10Y029
HAR	SP						Model No.	Page
							GW5D*C**M04	9 of 18
**: 30		CI	rromaticity	/ coordinat	tas	(Tolerance: (I _F = 700 mA	$x,y \pm 0.005)$, T _c = 25 °C)	
Range		Point 1	Point 2	Point 3	Point 4			
	Х	0.4310	0.4243	0.4384	0.4460			
	у	0.4100	0.3950	0.3950	0.4100			
Rank		Cł Point 1	romaticity Point 2	coordinat Point 3	tes Point 4			
1	X	0.4310	0.4243	0.4311	0.4383			
1	V	0.4100	0 3950	0 3950	0.4100			

0.4100

0.4460

2 0.3950 0.4100 0.4100 0.3950 у * The percentage of each rank in the shipment shall be determined by SHARP.

0.3950

0.4311

0.4100

0.4383

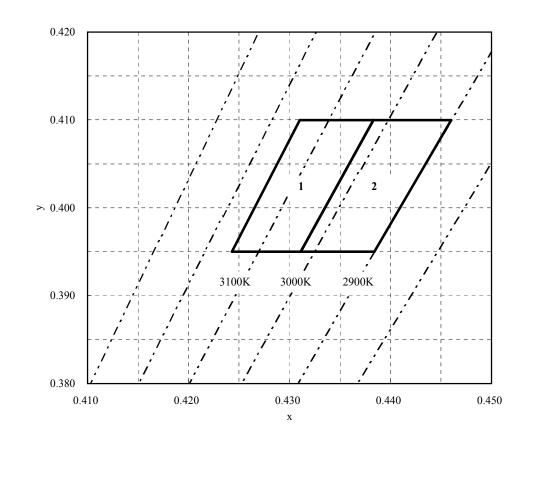
у

х

Chromaticity Diagram

0.3950

0.4384



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SHARP	Model No. GW5D*C**M04	Page 10 of 18
	(Tolerance: $x,y \pm 0.005$)	
	(Tolerance: x,y \pm 0.005) (I _F = 700 mA, T _c = 25 °C)	

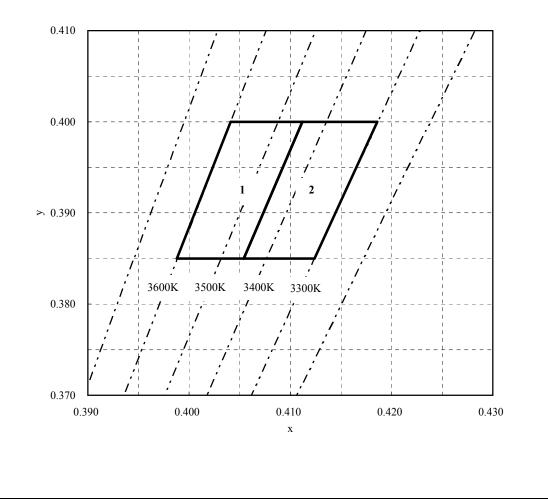
**: 35

Danga		Cł	romaticity	coordinat	tes
Range		Point 1	Point 2	Point 3	Point 4
\square	Х	0.4041	0.3988	0.4124	0.4186
	у	0.4000	0.3850	0.3850	0.4000

Rank		Cł	nromaticity	coordinat	tes
Nalik		Point 1	Point 2	Point 3	Point 4
1	х	0.4041	0.3988	0.4054	0.4112
1	у	0.4000	0.3850	0.3850	0.4000
2	х	0.4112	0.4054	0.4124	0.4186
2	у	0.4000	0.3850	0.3850	0.4000

* The percentage of each rank in the shipment shall be determined by SHARP.

Chromaticity Diagram



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	GW5D*C**M04 1	1 of 18

(Tolerance: x,y \pm 0.005) (I_F = 700 mA, T_c = 25 °C)

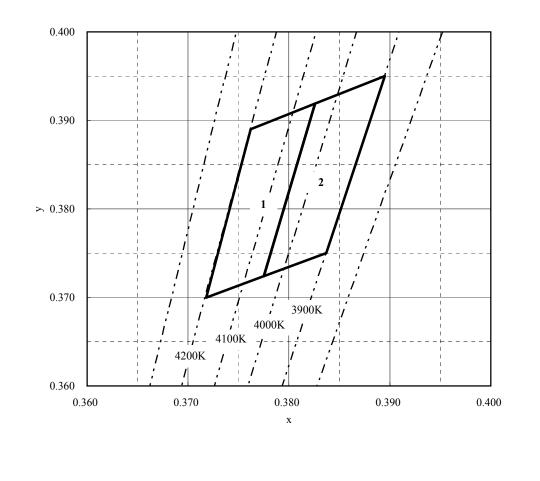
**: 40

Range		Cł	romaticity	coordinat	tes
Range		Point 1	Point 2	Point 3	Point 4
\square	х	0.3762	0.3718	0.3837	0.3895
	у	0.3890	0.3700	0.3750	0.3950

Rank		Cł	romaticity	coordinat	tes
Nalik		Point 1	Point 2	Point 3	Point 4
1	х	0.3762	0.3718	0.3775	0.3826
1	у	0.3890	0.3700	0.3724	0.3919
2	х	0.3826	0.3775	0.3837	0.3895
Z	у	0.3919	0.3724	0.3750	0.3950

* The percentage of each rank in the shipment shall be determined by SHARP.

Chromaticity Diagram



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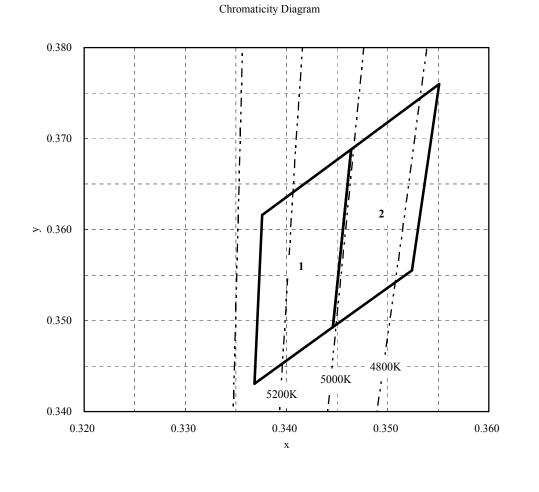
(Tolerance: x,y \pm 0.005) (I_F = 700 mA, T_c = 25 °C)

**: 50

Range		Cł	romaticity	coordinat	tes
Kange		Point 1	Point 2	Point 3	Point 4
\square	Х	0.3376	0.3369	0.3524	0.3551
	у	0.3616	0.3431	0.3555	0.3760

Rank		Cł	romaticity	coordinat	tes
Nalik		Point 1	Point 2	Point 3	Point 4
1	х	0.3376	0.3369	0.3446	0.3464
1	у	0.3616	0.3431	0.3493	0.3688
2	х	0.3464	0.3446	0.3524	0.3551
Z	у	0.3688	0.3493	0.3555	0.3760

* The percentage of each rank in the shipment shall be determined by SHARP.



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SHARP	Model No. Page	
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(Tolerance: x,y \pm 0.005) (I_F = 700 mA, T_c = 25 °C)

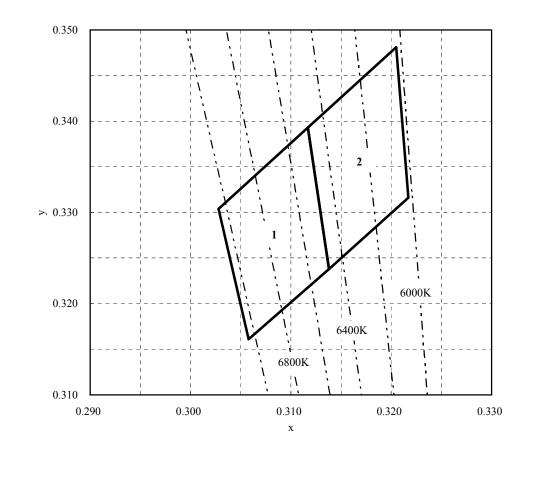
**: 65

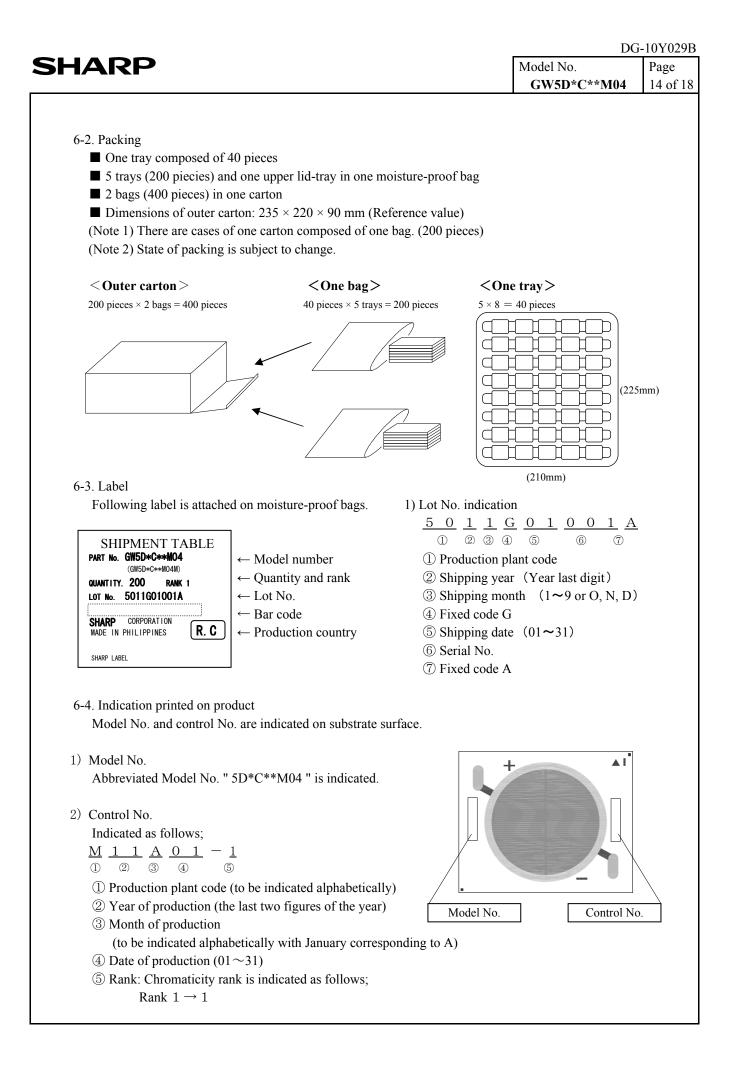
Danga		Cł	romaticity	coordinat	tes
Range		Point 1	Point 2	Point 3	Point 4
\square	Х	0.3028	0.3058	0.3217	0.3205
	у	0.3304	0.3161	0.3316	0.3481

Rank		Cł	nromaticity	coordinat	tes
Kalik		Point 1	Point 2	Point 3	Point 4
1	Х	0.3028	0.3058	0.3138	0.3117
1	у	0.3304	0.3161	0.3238	0.3393
2	х	0.3117	0.3138	0.3217	0.3205
2	v	0.3393	0.3238	0.3316	0.3481

* The percentage of each rank in the shipment shall be determined by SHARP.

Chromaticity Diagram





 7. Precautions (1) Storage conditions Please follow the conditions below. • Before opened: Temperature 5 ~ 30 °C, Relative humidity less than 60 %. (Before opened LED should be used within a year) • After opened: Temperature 5 ~ 30 °C, Relative humidity less than 60 %. (Please apply soldering within 1 week) • After opened LED should be kept in an aluminum moisture proof bag with a r absorbent material (silica gel). • Avoid exposing to air with corrosive gas. If exposed, electrode surface would be damaged, which may affect soldering. (2) Usage conditions This product is not designed for the use under any of the following conditions. Please confirm performance and reliability well enough if you use under any o • In a place with a lot of moisture, dew condensation, briny air, and corrosive g (Cl, H₂S, NH₃, SO₂, NO_X, etc.) • Under the direct sunlight, outdoor exposure, and in a dusty place. • In water, oil, medical fluid, and organic solvent. (3) Heat radiation If forward current (I_F) is applied to single-state module at any current, there is or emitting smoke. Equip with specified heat radiator, and avoid heat stuffed inside the module. (4) Installation Material of board is alumina ceramic. If installed inappropriately, trouble of no board and no succhest. 	the following condition	Pag 15 d
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Material of board is alumina ceramic. If installed inappropriately, trouble of no		
	radiation may occur di	ue to
board crack or overheat. Please take particular notice for installation.		
Refer to the following cautions on installation.Apply thermolysis adhesive, adhesive sheet or peculiar connector when more	ntad on hast radiator	
In case of applying adhesive or adhesive sheet only, check the effectiveness		fixino
If LED comes off from heat radiator, unusual temperature rise entails hazard	-	-
device deterioration, coming off of solder at leads, and emitting smoke.	I I I I I I I I I I I I I I I I I I I	0
• When LED device is mechanically fixed or locked, Please take into conside	ation regarding the me	ethod
attachment due to fail from stress.		
Avoid convexly uneven boards.		
Convex board is subject to substrate cracking or debasement of heat release.		
• It is recommended to apply adhesive or adhesive sheet with high thermal co	nductivity	
for radiation of heat effectively.		
• Please take care about the influence of color change of adhesive or adhesive	sheet in initial and lon	
period, which may affect light output or color due to change of reflectance f	1 1 1 1	ng tern

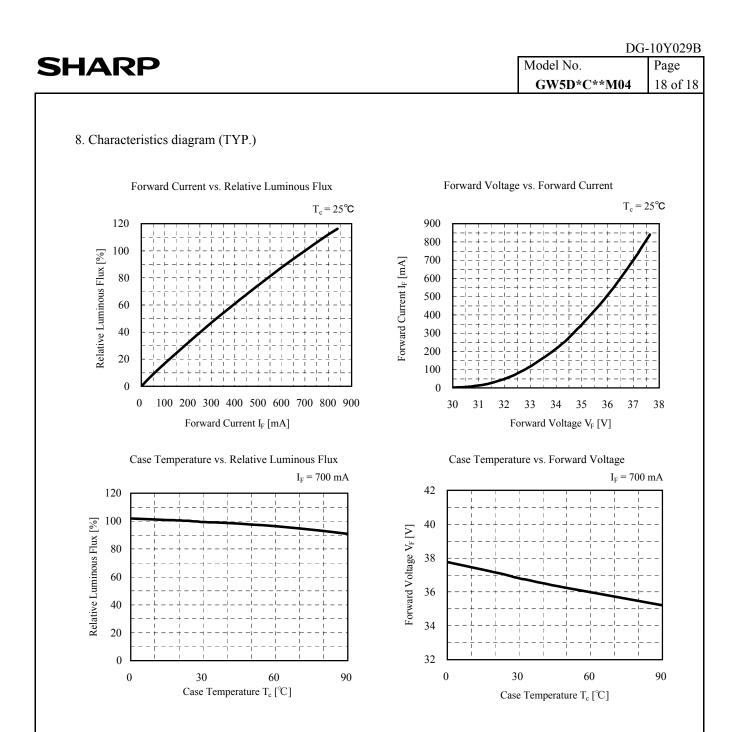
IARP	Model No. GW5D*C**M04	G-10Y029 Page 16 of 1
 Do not touch resin part including white resin part on the surface of LEI No light emission may occur due to damage of resin or cutting wire of When using tweezers, please handle by ceramic substrate part and avoi For mounting, please handle by side part of ceramic or the specified are 	LEDs by outer force. id touching resin part.	
Handling area		
(5) Connecting method		
In case of solder connecting method, follow the conditions mentioned bel	OW.	
• Use Soldering iron with thermo controller (tip temperature 380 $^{\circ}$ C), with		
• Secure the solderwettability on whole solder pad and leads.		
• During the soldering process, put the ceramic board on materials whose	conductivity is poor enough	1
not to radiate heat of soldering.		
• Warm up (with using a heated plate) the substrate is recommended befo (preheat condition: 100 $^{\circ}$ C ~ 150 $^{\circ}$ C, within 60 sec)	ore soldering.	
Avoid touching a part of resin with soldering iron.		
• This product is not designed for reflow and flow soldering.		
• Avoid such lead arrangement as applying stress to solder-applied area.		
• Please do not detach solder and make re-solder.		
Please solder evenly on each electrodes.		
Please prevent flux from touching to resin.		
6 Static electricity		
This product is subject to static electricity, so take measures to cope with	it.	
Install circuit protection device to drive circuit, if necessary.		
⑦ Drive method		
• Any reverse voltage cannot be applied to LEDs when they are in operation		
Design a circuit so that any flow of reverse or forward voltage can not be	e applied to LEDs	
when they are out of operation.		
 Module is composed of LEDs connected in both series and parallel. Constant voltage power supply runs off more than specified current amount 	unt due to lowered V $_{\rm F}$	
caused by temperature rise.		
Constant current power supply is recommended to drive.		
® Cleaning		
Avoid cleaning, since silicone resin is eroded by cleaning.		
O Color-tone variation O		
Chromaticity of this product is monitored by integrating sphere right after	the operation.	
Chromaticity varies depending on measuring method, light spread conditi		
Please verify your actual conditions before use.		

	DG-10	DG-10Y029B	
SHARP	Model No. Pa	age	
	GW5D*C**M04 1'	7 of 18	

- 10 Safety
 - •Please prevent to see lighting LED devices directly at any moment for safety your eyes.
 - ·Looking light from LEDs for a long time may result in hurt your eyes.
 - •In case that excess current (over ratings) are supplied to the device, hazardous phenomena including abnormal heat generation, emitting smoke, or catching fire can be caused.
 - Take appropriate measures to excess current and voltage.
 - In case of solder connecting method, there is a possibility of fatigue failure by heat.
 - Please fix the leads in such case to protect from short circuit or leakage of electricity caused by contact.
 - •Please confirm the safety standards or regulations of application devices.
 - Please careful not to injure your hand by edge of ceramic substrate.
- 1 Other cautions
 - Guarantee covers the compliance to the quality standards mentioned in the Specifications,

however it does not cover the compatibility with application of the end-use, including assembly and usage environment.

In case any quality problems occurred in the application of end-use, details will be separately discussed and determined between the parties hereto.



(Note) Characteristics data shown here are for reference purpose only. (Not guaranteed data)